

Bill of Materials

TI DESIGNS

TIDA-00827

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Package
1	1	!PCB1	n/a	Printed Circuit Board	Any	TIDA-00827	
2	3	C1, C2, C3	22uF	CAP, CERM, 22 μ F, 35 V, +/- 20%, X5R, 0805	TDK	C2012X5R1V226M125AC	805
3	3	C4, C6, C7	1500pF	CAP, CERM, 1500 pF, 16 V, +/- 10%, X7R, 0603	TDK	CGA1A2X7R1C152K030BA	603
4	4	C5, C8, C16, C18	0.1uF	CAP, CERM, 0.1 μ F, 6.3 V, +/- 10%, X7R, 0603	MuRata	GRM188R70J104KA01D	603
5	1	C9	0.01uF	CAP, CERM, 0.01 μ F, 50 V, +/- 10%, X7R, 0603	TDK	C1608X7R1H103K	603
6	1	C10	0.1uF	CAP, CERM, 0.1 μ F, 16 V, +/- 10%, X7R, 0603	TDK	C1608X7R1C104K	603
7	2	C11, C12	0.1uF	CAP, CERM, 0.1 μ F, 50 V, +/- 10%, X7R, 0603	TDK	C1608X7R1H104K	603
8	1	C13	10uF	CAP, CERM, 10 μ F, 35 V, +/- 10%, X7R, 1206	Taiyo Yuden	GMK316AB7106KL	1206
9	1	C14	0.47uF	CAP, CERM, 0.47 μ F, 6.3 V, +/- 10%, X7R, 0603	MuRata	GRM188R70J474KA01D	603
10	1	C15	4.7uF	CAP, CERM, 4.7 μ F, 10 V, +/- 10%, X7R, 0805	MuRata	GRM21BR71A475KA73L	805
11	1	C17	1000pF	CAP, CERM, 1000pF, 16V, +/-10%, X7R, 0603	MuRata	GRM188R71C102KA01D	603
12	1	D1	Green	LED, Green, SMD	Lite-On	LTST-C171GKT	LED_0805
13	1	J1	1x5	Header, 100mil, 5x1, Gold, TH	Samtec	HTSW-105-07-G-S	Header, 100mil, 5x1, TH
14	1	J2	1x2	Header, 100mil, 2x1, Gold, TH	Sullins Connector Solutions	PBC02SAAN	100mil, 1x2, 230 mil
15	1	J3	1x3	Header, 100mil, 3x1, Gold, TH	Sullins Connector Solutions	PBC03SAAN	PBC03SAAN
16	1	J4	1x4	SOCKET .050" GRID SIP 4 POS R/A, TH	Mill-Max	851-43-004-20-001000	R/A 4x1 receptacle
17	1	J5	1x6	Header, 100mil, 6x1, Tin, TH	Sullins Connector Solutions	PEC06SAAN	608x100mil, Pitch 100mil
18	2	R1, R10	47k	RES, 47k ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW060347K0JNEA	603
19	3	R2, R3, R4	1.0k	RES, 1.0 k, 5%, 0.1 W, 0603	Vishay-Dale	CRCW06031K00JNEA	603
20	1	R5	50k	Trimming Potentiometer, 50K, 0.5W, TH	Bourns	3352T-1-503LF	9.53x8.89mm
21	1	R6	100k	RES, 100 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW0603100KFKEA	603
22	1	R7	330	RES, 330 ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW0603330RJNEA	603
23	1	R8	10.0k	RES, 10.0 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW060310K0FKEA	603
24	3	R9, R12, R14	10k	RES, 10 k, 5%, 0.1 W, 0603	Vishay-Dale	CRCW060310K0JNEA	603
25	1	R11	0	RES, 0 ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW06030000Z0EA	603
26	1	R13	200k	RES, 200 k, 5%, 0.1 W, 0603	Vishay-Dale	CRCW0603200KJNEA	603
27	1	R15	0.1	RES, 0.1, 1%, 0.5 W, 1206	Stackpole Electronics Inc	CSR1206FKR100	1206
28	1	S1	SPST	Switch, Tactile, SPST-NO, 0.05A, 12V, SMT	TE Connectivity	4-1437565-1	SW, SPST 6x6 mm
29	1	U1	MCU	h 4 KB Flash, 256 B SRAM and 24 GPIOs, -40 to 85 degC, 2	Texas Instruments	MSP430G2353IPW20	PW0020A
30	1	U2	DRV	2.5-A Triple 1/2-H Bridge Driver, RHH0036C	Texas Instruments	DRV8313RHR	RHH0036C
31	0	FID1, FID2, FID3	n/a	Fiducial mark. There is nothing to buy or mount.	N/A	N/A	Fiducial

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